Special Issue

Synergies in Steganalysis, Imaging, Medicine, and Thermal Systems

Message from the Guest Editors

This Special Issue, titled "Synergies in Steganalysis, Imaging, Medicine, and Thermal Systems", focuses on the intersection of diverse yet interconnected fields, exploring innovative methods and applications. It invites research contributions on advancements in steganalysis for secure data communication, image processing techniques for enhanced analysis, biomedical imaging and diagnostics, and thermal system optimization for industrial and medical applications. This Special Issue will bridge gaps, foster interdisciplinary collaborations, and highlight how these domains can collectively address technological challenges and improve practical outcomes. Both theoretical and experimental studies are welcome.

Guest Editors

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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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